

WATER RESISTANT WOOD GLUE

Revision 07/03/2007

Page 1 of 2

TECHNICAL DATA:	<p>Base: PVAc dispersion Consistency: High viscous liquid Curing system: Physical drying Viscosity in mPa.s (Brookfield RVT 5/20): 8000-15000 Density (DIN 53479): Ca. 1,1 g/cm³ Total solid content (%): 45,0 – 47,0 pH: 2,5 – 3,5 Minimum Film Forming Temperature (°C): 5 Open time(*): 8 minutes Pressing time: see under Application Pressing pressure: 1 - 2 kg/cm² Water resistance (according to DIN EN 204): D3 Coverage (full surface bonding): Ca. 80 – 140 g/m² Coverage (assembly): Ca. 160 – 180 g/m² * This varies according to ambient conditions such as temperature, humidity, substrate etc.</p>
PRODUCT:	Water Resistant Wood Glue is a ready to use PVAc-based wood adhesive with a high durability (D3).
CHARACTERISTICS:	Easy application Transparent when dry High bond strength Fast drying Resistant to high temperatures
APPLICATIONS:	Interior applications with frequent short-term exposure of the bonds to running or condensed water Interior applications with long-term exposure of the bonds to high humidity Exterior applications which are not exposed to weather Manufacturing of door and window-frames that need to meet class D3 according to EN204. Bonding of wood, board, chipboard, veneer Mounting of soft wood Construction bonding such as mortise and tenon joints, punches, etc. Stationary edge-banding with veneers, plastic laminates and solid wood strips Surface bonding of decor-finish film, HPL and CPL to chipboard, MDF and Triplex Bonding joints in boards and block bonding of softwood, hardwood and chipboard
PACKAGING:	Colour: white Packaging: available in 20 ltr., 5 ltr., 1 ltr. and 500 ml
SHELF LIFE:	At least 12 months in unopened packaging in a cool and dry storage place at temperatures between +5°C and +25°C. Do not expose to frost.

Remark: The directives contained in this documentation are the result of our experiments and of our experience and have been submitted in good faith. Because of the diversity of the materials and substrates and the great number of possible applications which are out of our control, we cannot accept any responsibility for the results obtained. In every case it is recommended to carry out preliminary experiments.

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Revision: 19/06/2007

Page 2 of 2

SURFACES:

Type: porous materials such as wood, cardboard, laminate etc.

State of Surface: the to be bonded materials should be flat and well fitting as well as clean, dry and free of dust and grease. Large tolerances will cause a longer curing time and a lower final bond strength.

Preliminary treatment: sanding of smooth substrates improves the adhesion strength

We recommend a preliminary compatibility test.

APPLICATION:

Method: apply the adhesive by means of a brush, notched trowel or mechanically to one of the to be bonded substrates. Join the parts together and press for 1 - 2 hours.

Application temperature: Temperature of working space, adhesive and substrates 18°C to 20°C

Pressing times: if applicable; the curing time depends strongly on the used kind of wood, temperature, amount of adhesive, the porosity of the materials to be bonded and the production rate.

Minimum pressing times:

High-frequency bonding with longitudinal heating	> 15 sec.
Dekor-finish	5 – 10 sec.
assembly bondings	8 – 15 min.
bonding joints and block bonding	10 – 15 min.

Surface bonding of HPL/CPL in short cycle presses at 70°C

to plywood	approx. 90 sec.
to chipboard	approx. 45 sec.

Clean: Uncured Water Resistant Wood Glue may be removed from materials and tools with water. Cured adhesive must be removed mechanically.

Repair: with Water Resistant Wood Glue

HEALTH- AND SAFETY RECOMMENDATIONS:

Apply the usual industrial hygiene.
Consult the label for more information.

REMARKS:

When bonding certain kinds of wood, such as oak or tropical hardwood, discoloration may occur.
Do not dilute the adhesive

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